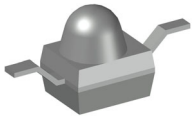


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

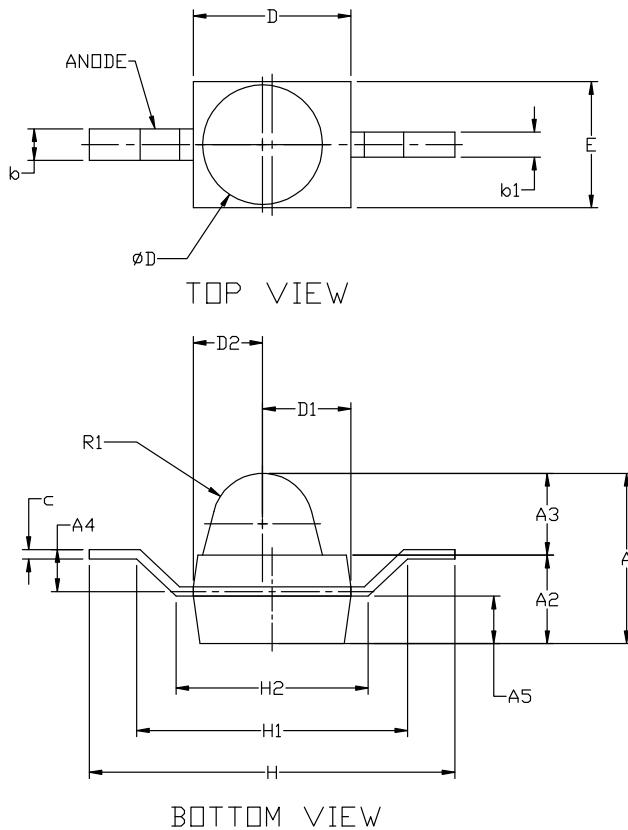


**T-3/4 2.50x2.00**  
**CASE 100EG**  
**ISSUE O**

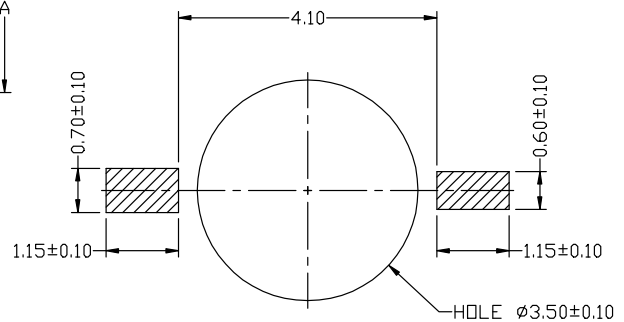
DATE 14 SEP 2023

**NOTES:**

1. CONTROLLING DIMENSIONS: MILLIMETERS
2. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
3. 2MM ZBEND LED RP.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.500	2.700	2.900
A2	1.300	1.400	1.500
A3	1.200	1.300	1.400
A4	0.550	0.650	0.750
A5	0.650	0.750	0.850
b	0.450	0.550	0.650
b1	0.350	0.450	0.550
c	0.100	0.150	0.200
D	2.300	2.500	2.700
D1	1.200	1.400	1.600
D2	0.900	1.100	1.300
E	1.800	2.000	2.200
H	5.600	5.800	6.000
H1	4.100	4.300	4.500
H2	2.850	3.050	3.250
∅D	1.700	1.900	2.100
R1	0.700	0.800	0.900



**RECOMMENDED MOUNTING FOOTPRINT\***  
 \*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>T-3/4 2.50x2.00</b>	<b>PAGE 1 OF 1</b>

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